

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT												
NATURE OF CONVEYANCE:	Corrective Assignment to correct the Assignee's name previously recorded on Reel 020649 Frame 0361. Assignor(s) hereby confirms the correction of Assignee's name from TAIWAN SEMICONDUCTOR COMPANY, LTD. to TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD..												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Burn Jeng LIN</td><td>02/23/2008</td></tr><tr><td>Hsin-Chang LEE</td><td>02/15/2008</td></tr><tr><td>Ming-Jiun YAO</td><td>02/15/2008</td></tr></tbody></table>		Name	Execution Date	Burn Jeng LIN	02/23/2008	Hsin-Chang LEE	02/15/2008	Ming-Jiun YAO	02/15/2008				
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<table border="1"><tr><td>Name:</td><td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td></tr><tr><td>Street Address:</td><td>No. 8, Li-Hsin Rd. 6</td></tr><tr><td>Internal Address:</td><td>Science-Based Industrial Park</td></tr><tr><td>City:</td><td>Hsin-Chu</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr><tr><td>Postal Code:</td><td>300-77</td></tr></table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA													
Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone: 9727398635													
Email: lydia.eppshilliard@haynesboone.com													
Correspondent Name: David M. O'Dell													
Address Line 1: Haynes and Boone, LLP													
Address Line 2: 901 Main Street, Suite 3100													
Address Line 4: Dallas, TEXAS 75202													
ATTORNEY DOCKET NUMBER:	24061.956												

CH \$40.00 12029275

500537105

PATENT
REEL: 020935 FRAME: 0466

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 4

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TO: DAVID M. O'DELL COMPANY: HAYNES AND BOONE, LLP

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.103/13/2008
500487203

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
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Total Attachments: 2													

CH \$40.00 12029275

TO: DAVID M. O'DELL COMPANY: HAYNES AND BOONE, LLP

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|--|
| (1) | Burn Jeng Lin | of | 153 Guang Fu Road, Sec. 1, Lane 89
Hsin-Chu, Taiwan, R.O.C. |
| (2) | Hsin-Chang Lee | of | No. 121, Wen-Hua Road, Wen-Shan Li
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Ming-Jiun Yao | of | |

have invented certain improvements in

PELLICLE STRESS RELIEF

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on February 11, 2008 and assigned application number 12/029,275; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

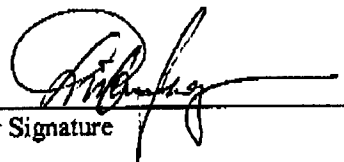
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Burn Jeng Lin

Residence Address: 153 Guang Fu Road, Sec. 1, Lane 89
Hsin-Chu, Taiwan, R.O.C.


Dated: Feb 23, 2008


Inventor Signature

Inventor Name: Hsin-Chang Lee

Residence Address: No. 121, Wen-Hua Road, Wen-Shan Li
Hsin-Chu, Taiwan, R.O.C.

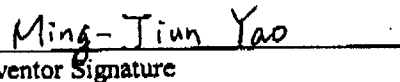
Dated: 2.15.2008


Inventor Signature

Inventor Name: Ming-Jiun Yao

Residence Address: 2F., NO.9-1, Alley 1, Lane 92, Yongyi st., Xiaogang District
Kaohsiung City 812, Taiwan (R.O.C)

Dated: 2.15.2008


Inventor Signature